L Number	Hits	Search Text	DB	Time stamp
-	28	"5608257"	USPAT	2004/09/22 14:56
-	2	"63122150"	EPO; JPO; DERWENT; IBM TDB	2004/03/31 16:51
-	6	<pre>(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/22 15:20
-	6	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 17:00
-	15	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
_	9	<pre>((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)) not ((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and substrate)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 16:56
_	8	•	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 17:05
-	2	((chip or die or ic or (integrated adj circuit)) and (fuse same cuttable) and substrate) not ((chip or die or ic or (integrated adj circuit)) and (fuse with	USPĀT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/31 17:00
-	13122	cuttable)) (chip or die or ic or (integrated adj circuit)) and fuse and substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/31 17:07
-	427	((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
	241	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
_	1	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic with series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:07
_	4	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic SAME series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:07
_	7	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
-	16	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20

				•
-	267	(((chip or die or ic or (integrated adj	USPAT;	2004/09/22 15:20
		circuit)) and fuse and substrate) and	US-PGPUB;	<u> </u>
		(bonding adj pad)) and cut\$5	EPO; JPO;	
			DERWENT;	1
	100	//	IBM_TDB USPAT;	2004/00/22 15-21
_	469	' '	USPAT; US-PGPUB;	2004/09/22 15:21
		circuit)) and fuse and substrate) and (bonding adj pad)	EPO; JPO;	
		(boliding ad) pad)	DERWENT;	
			IBM TDB	
	146	((((chip or die or ic or (integrated adj	USPAT;	2004/09/22 15:21
		circuit)) and fuse and substrate) and	US-PGPUB;	
		(bonding adj pad)) and cut\$5) and logic	EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	218	` ` ` <u> </u>	USPAT;	2004/09/22 15:23
		circuit)) and fuse and substrate) and	US-PGPUB;	
		(bonding adj pad)) and logic	EPO; JPO;	
			DERWENT;	
		,,,,,,,, ,,,,,,,,,,,,,,,,,,,,,,,,,,,	IBM_TDB	
-	157		USPAT;	2004/09/22 15:23
		circuit)) and fuse and substrate) and	US-PGPUB;	
		(bonding adj pad)) and logic) and series	EPO; JPO; DERWENT;	
			IBM TDB	
1_	107	(((((chip or die or ic or (integrated adj	USPAT;	2004/09/22 15:29
_	10/	circuit)) and fuse and substrate) and	US-PGPUB;	2007/09/22 15:29
		(bonding adj pad)) and cut\$5) and logic)	EPO; JPO;	
		and series	DERWENT;	
]			IBM TDB	
-	375	257/665.ccls.	USPAT;	2004/09/22 15:49
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	375	257/528.ccls.	USPAT;	2004/09/22 15:50
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	·
	734	257/529.ccls.	IBM_TDB USPAT;	2004/09/22 15:50
-	/34	257/529.CCIS.	US-PGPUB;	2004/09/22 15:50
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	.1324	257/777.ccls.	USPAT;	2004/09/22 17:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1762	257/784.ccls.	USPAT;	2004/09/22 15:50
İ			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
	1.000	257/706 2212	IBM_TDB	2004/00/20 17 21
-	1607	257/786.ccls.	USPAT;	2004/09/22 17:31
			US-PGPUB; EPO; JPO;	
	1		DERWENT;	
	-		IBM TDB	
_	1192	257/777.ccls. not 257/784.ccls.	USPAT;	2004/09/22 17:31
	1172		US-PGPUB;	= 301, 03, 22 1, 131
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	1553	257/786.ccls. not (257/777.ccls. not	USPAT;	2004/09/22 17:31
		257/784.ccls.)	US-PGPUB;	
	ł		EPO; JPO;	
			DERWENT;	
L	<u> </u>		IBM_TDB	